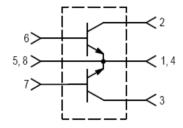


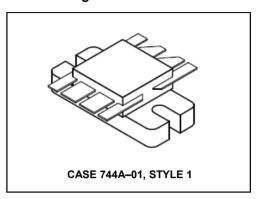
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Designed primarily for wideband large—signal output and driver amplifier stages in the 30 to 500 MHz frequency range.

- Specified 28 V, 500 MHz characteristics —
 Output power = 100 W
 Typical gain = 9.5 dB (Class AB); 8.5 dB (Class C)
 Efficiency = 55% (typ.)
- Built-in input impedance matching networks for broadband operation
- Push-pull configuration reduces even numbered harmonics
- Gold metallization system for high reliability
- 100% tested for load mismatch



Product Image



The MRF393 is two transistors in a single package with separate base and collector leads and emitters common. This arrangement provides the designer with a space saving device capable of operation in a push–pull configuration.

PUSH-PULL TRANSISTORS

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Collector–Emitter Voltage	VCEO	30	Vdc
Collector-Base Voltage	V _{CBO}	60	Vdc
Emitter-Base Voltage	VEBO	4.0	Vdc
Collector Current — Continuous	IC	16	Adc
Total Device Dissipation @ T _C = 25°C (1) Derate above 25°C	PD	270 1.54	Watts W/°C
Storage Temperature Range	T _{stg}	-65 to +150	°C
Junction Temperature	TJ	200	°C

THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Thermal Resistance, Junction to Case	R _e JC	0.65	°C/W

NOTE:

This device is designed for RF operation. The total device dissipation rating applies only when the device is operated as an RF push-pull
amplifier.

MRF393



The RF Line Controlled "Q" Broadband Power Transistor 100W, 30 to 500MHz, 28V

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ELECTRICAL CHARACTERISTICS (T_C = 25°C unless otherwise noted.)

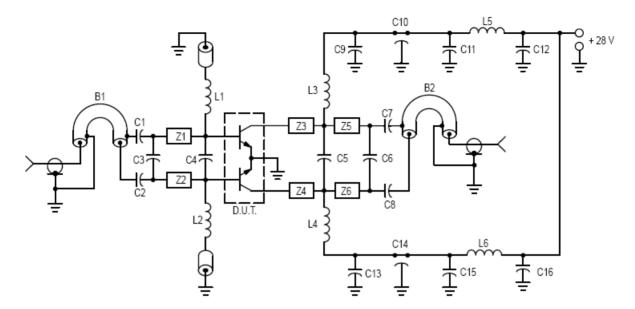
Characteristic	Symbol	Min	Тур	Max	Unit
OFF CHARACTERISTICS (1)					
Collector–Emitter Breakdown Voltage (I _C = 50 mAdc, I _B = 0)	V(BR)CEO	30	_	_	Vdc
Collector–Emitter Breakdown Voltage (I _C = 50 mAdc, V _{BE} = 0)	V(BR)CES	60	_	_	Vdc
Emitter–Base Breakdown Voltage (I _E = 5.0 mAdc, I _C = 0)	V(BR)EBO	4.0	_	_	Vdc
Collector Cutoff Current (V _{CB} = 30 Vdc, I _E = 0)	ICBO	_	_	5.0	mAdc
ON CHARACTERISTICS (1)					
DC Current Gain (I _C = 1.0 Adc, V _{CE} = 5.0 Vdc)	hFE	20	_	100	_
DYNAMIC CHARACTERISTICS (1)				•	
Output Capacitance (V _{CB} = 28 Vdc, I _E = 0, f = 1.0 MHz)	C _{ob}	40	75	95	pF
FUNCTIONAL TESTS (2) — See Figure 1				•	
Common–Emitter Amplifier Power Gain (V _{CC} = 28 Vdc, P _{out} = 100 W, f = 500 MHz)	G _{pe}	7.5	8.5	_	dB
Collector Efficiency (V _{CC} = 28 Vdc, P _{out} = 100 W, f = 500 MHz)	η	50	55	_	%
Load Mismatch (V _{CC} = 28 Vdc, P _{out} = 100 W, f = 500 MHz, VSWR = 30:1, all phase angles)	Ψ	No Degradation in Output Power			

NOTES:

- 1. Each transistor chip measured separately.
- 2. Both transistor chips operating in push-pull amplifier.



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C1, C2, C7, C8 - 240 pF 100 mil Chip Cap

C3 - 15 pF 100 mil Chip Cap

C4 — 24 pF 100 mil Chip Cap

C5 - 33 pF 100 mil Chip Cap

C6 - 12 pF 100 mil Chip Cap

C9, C13 - 1000 pF 100 mil Chip Cap

C10, C14 — 680 pF Feedthru Cap

C11, C15 - 0.1 µF Ceramic Disc Cap

C12, C16 - 50 µF 50 V

L1, L2 - 0.15 μH Molded Choke with Ferrite Bead

L3, L4 - 2-1/2 Turns #20 AWG 0.200" ID

L5, L6 - 3-1/2 Turns #18 AWG 0.200" ID

B1, B2 — Balun 50 Ω Semi Rigid Coax, 86 mil OD, 4" Long

Z1, Z2 - 850 mil Long x 125 mil W. Microstrip

Z3, Z4 - 200 mil Long x 125 mil W. Microstrip

Z5, Z6 - 800 mil Long x 125 mil W. Microstrip

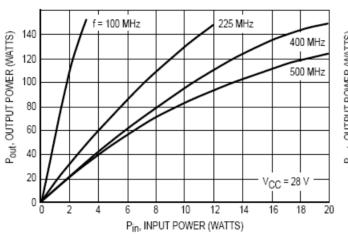
Board Material — 0.0325" Teflon–Fiberglass, ϵ_Γ = 2.56, 1 oz. Copper Clad both sides.

Figure 1. 500 MHz Test Fixture



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CLASS C



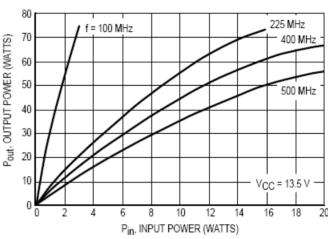
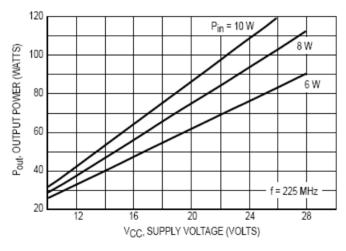


Figure 2. Output Power versus Input Power

Figure 3. Output Power versus Input Power

CLASS C



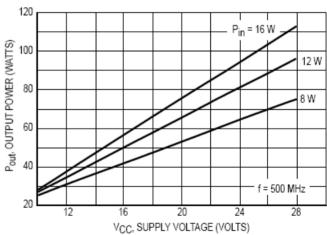
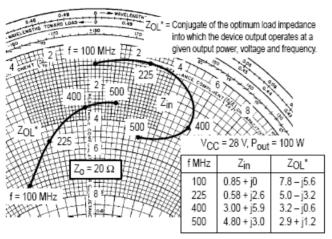


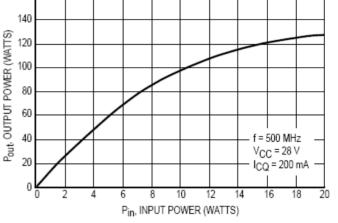
Figure 4. Output Power versus Supply Voltage

Figure 5. Output Power versus Supply Voltage



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NOTE: Z_{in} & Z_{OL}* are given from base–to–base and collector–to–collector respectively.

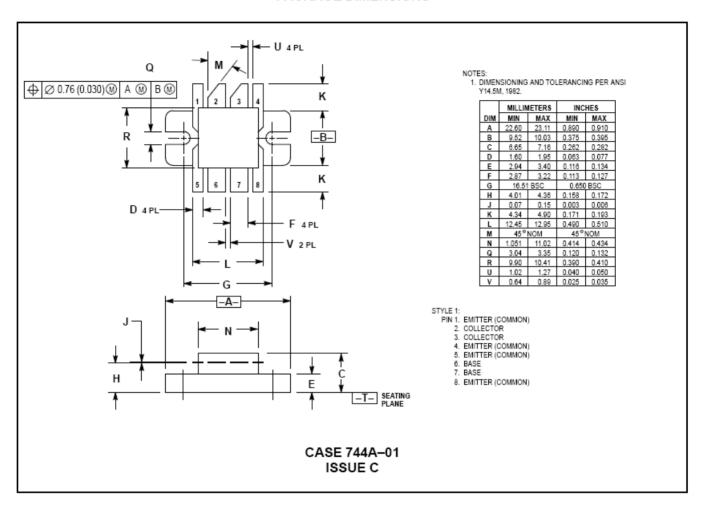
Figure 6. Series Equivalent Input/Output Impedance

Figure 7. Class AB Output Power versus Input Power



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PACKAGE DIMENSIONS



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